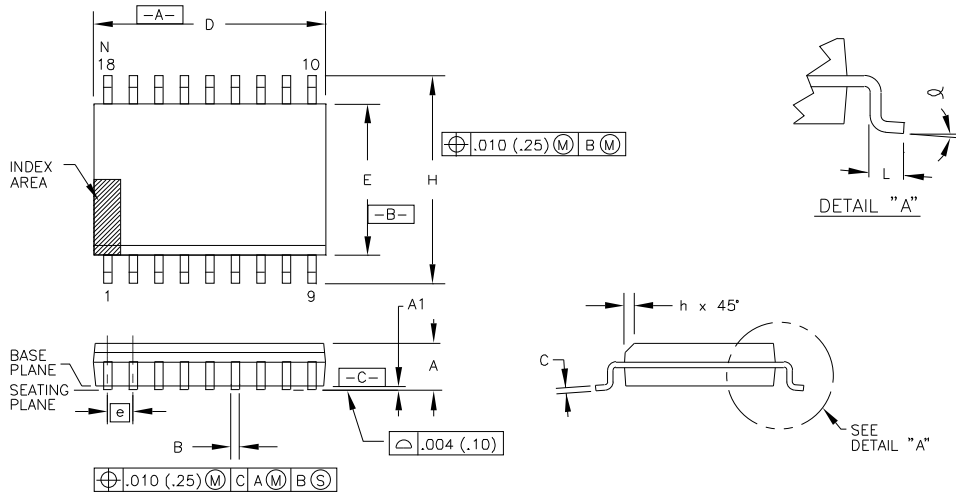


Package Number 219 - 18-LEAD SOIC



| DIM | INCHES | | MILLIMETERS | | N | D | INCHES | | MILLIMETERS | | N |
|-------|--------|-------|-------------|-------|---|---|--------|------|-------------|------|---|
| | MIN. | MAX. | MIN. | MAX. | | | MIN. | MAX. | MIN. | MAX. | |
| A | .0926 | .1043 | 2.35 | 2.65 | | | | | | | |
| A1 | .004 | .0118 | 0.10 | 0.30 | | | | | | | |
| B | .013 | .020 | 0.33 | 0.51 | 7 | | | | | | |
| C | .0091 | .0125 | 0.23 | 0.32 | | | | | | | |
| D | .4469 | .4625 | 11.35 | 11.75 | 2 | | | | | | |
| E | .2914 | .2992 | 7.40 | 7.60 | 3 | | | | | | |
| e | .050 | BASIC | 1.27 | BASIC | | | | | | | |
| H | .394 | .419 | 10.00 | 10.65 | | | | | | | |
| h | .010 | .029 | 0.25 | 0.75 | 4 | | | | | | |
| L | .016 | .050 | 0.40 | 1.27 | 5 | | | | | | |
| N | 18 | | 18 | | 6 | | | | | | |
| alpha | 0° | 8° | 0° | 8° | | | | | | | |

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
- DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
- THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT,

A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

- L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- N IS THE NUMBER OF TERMINAL POSITIONS.
- THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
- LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.

PACKAGE NUMBER: ZZZ19 REV.: E
JEDEC NUMBER: MS-013-AB



PACKAGE DRAWING

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